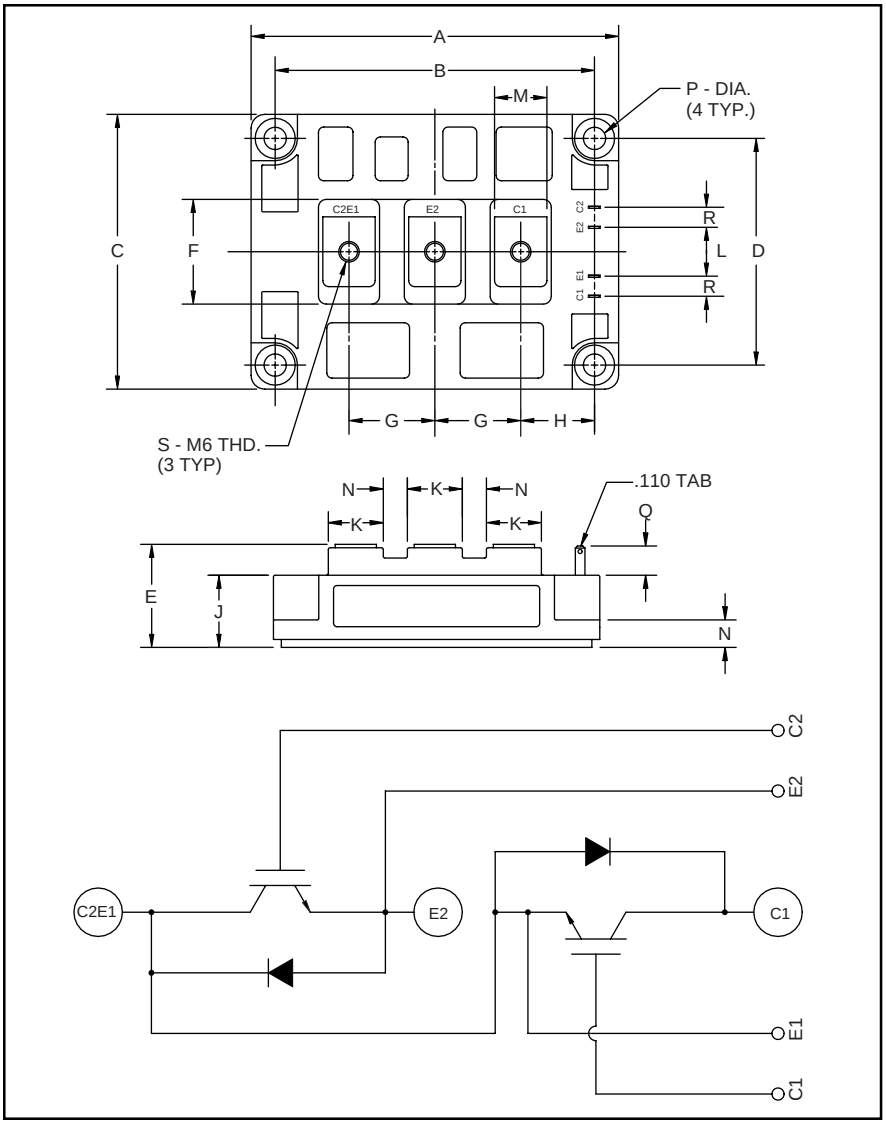
Powerex, Inc., 200 Hillis Street, Youngwood, Pennsylvania 15697-1800 (724) 925-7272

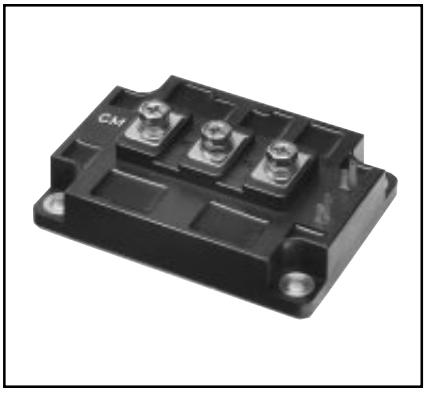
Dual IGBTMOD™ H-Series Module
300 Amperes/1400 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.661±0.01	93.0±0.25
C	3.15	80.0
D	2.441±0.01	62.0±0.25
E	1.18 Max.	30.0 Max.
F	1.18	30.0
G	0.98	25.0
H	0.85	21.5
J	0.83	21.2

Dimensions	Inches	Millimeters
K	0.71	18.0
L	0.59	15.0
M	0.55	14.0
N	0.28	7.0
P	0.26 Dia.	Dia. 6.5
Q	0.33	8.5
R	0.24	6.0
S	M6 Metric	M6



Description:
Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:
- ☐ Low Drive Power
- ☐ Low $V_{CE(sat)}$
- ☐ Discrete Super-Fast Recovery (135ns) Free-Wheel Diode
- ☐ High Frequency Operation (20-25kHz)
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:
- ☐ AC Motor Control
- ☐ Motion/Servo Control
- ☐ UPS
- ☐ Welding Power Supplies
- ☐ Laser Power Supplies

Ordering Information:
Example: Select the complete part module number you desire from the table below -i.e. CM300DY-28H is a 1400V (V_{CES}), 300 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	300	28

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Absolute Maximum Ratings, T_j = 25 °C unless otherwise specified

Ratings	Symbol	CM300DY-28H	Units
Junction Temperature	T_j	–40 to 150	°C
Storage Temperature	T_{stg}	–40 to 125	°C
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	1400	Volts
Gate-Emitter Voltage	V_{GES}	±20	Volts
Collector Current	I_C	300	Amperes
Peak Collector Current	I_{CM}	600*	Amperes
Diode Forward Current	I_F	300	Amperes
Diode Forward Surge Current	I_{FM}	600*	Amperes
Power Dissipation	P_d	2100	Watts
Max. Mounting Torque M6 Terminal Screws	–	26	in-lb
Max. Mounting Torque M6 Mounting Screws	–	26	in-lb
Module Weight (Typical)	–	500	Grams
V Isolation	V_{RMS}	2500	Volts

* Pulse width and repetition rate should be such that device junction temperature does not exceed the device rating.

Static Electrical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}$, V_{GE} = 0V	–	–	1.0	mA
Gate Leakage Current	I_{GES}	$V_{GE} = V_{GES}$, V_{CE} = 0V	–	–	0.5	μA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	I_C = 30mA, V_{CE} = 10V	5.0	6.5	8.0	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_C = 300A, V_{GE} = 15V	–	3.1	4.2**	Volts
		I_C = 300A, V_{GE} = 15V, T_j = 150°C	–	2.95	–	Volts
Total Gate Charge	Q_G	V_{CC} = 600V, I_C = 300A, V_{GE} = 15V	–	1530	–	nC
Diode Forward Voltage	V_{FM}	I_E = 300A, V_{GE} = 0V	–	–	3.8	Volts

** Pulse width and repetition rate should be such that device junction temperature rise is negligible.

Dynamic Electrical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics		Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance		C_{ies}	V_{GE} = 0V, V_{CE} = 10V, f = 1MHz	–	–	60	nF
Output Capacitance		C_{oes}		–	–	21	nF
Reverse Transfer Capacitance		C_{res}		–	–	12	nF
Resistive	Turn-on Delay Time	$t_{d(on)}$	V_{CC} = 800V, I_C = 300A, $V_{GE1} = V_{GE2}$ = 15V, R_G = 1.0Ω	–	–	250	ns
Load	Rise Time	t_r		–	–	500	ns
Switching	Turn-off Delay Time	$t_{d(off)}$		–	–	350	ns
Times	Fall Time	t_f		–	–	500	ns
Diode Reverse Recovery Time		t_{rr}	I_E = 300A, di_E/dt = –600A/μs	–	–	300	ns
Diode Reverse Recovery Charge		Q_{rr}	I_E = 300A, di_E/dt = –600A/μs	–	3.0	–	μC

Thermal and Mechanical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per IGBT	–	–	0.06	°C/W
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per FWDi	–	–	0.12	°C/W
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	–	–	0.035	°C/W

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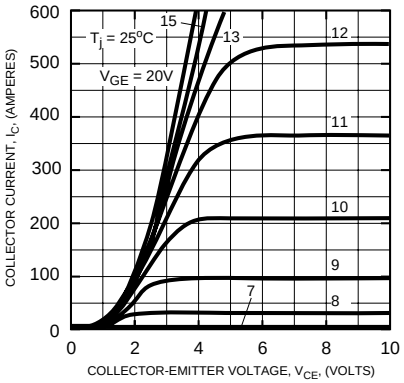
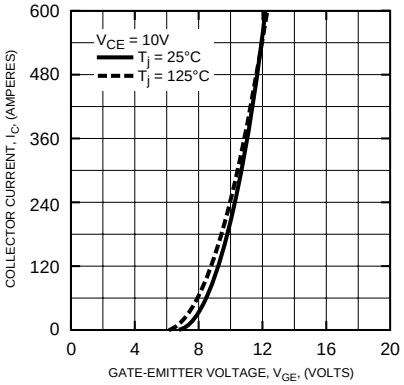
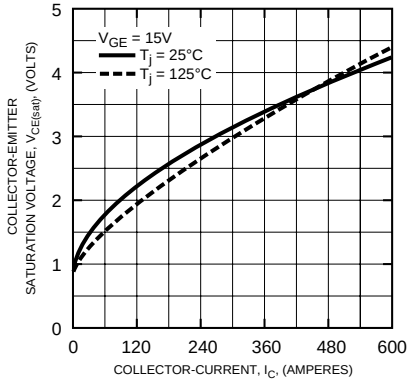
OUTPUT CHARACTERISTICS (TYPICAL)



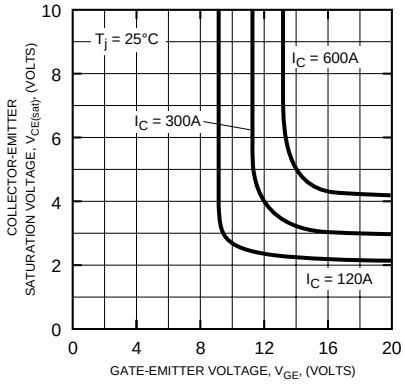
TRANSFER CHARACTERISTICS (TYPICAL)



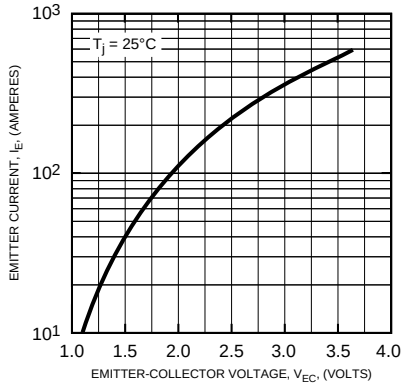
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



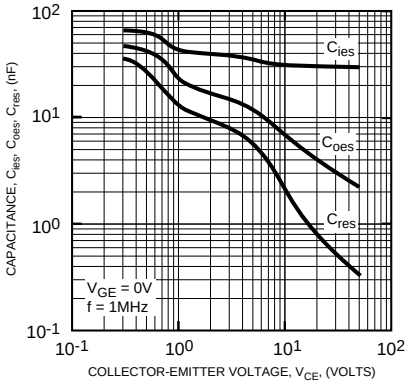
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



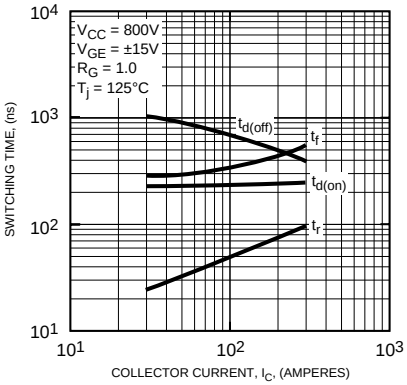
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



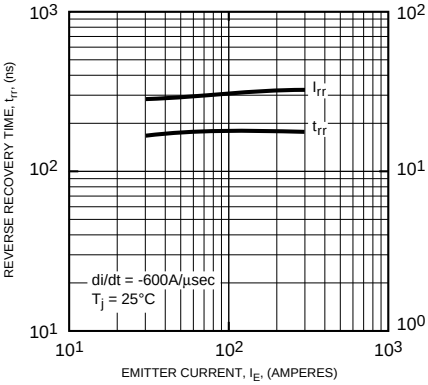
CAPACITANCE VS. V_{CE} (TYPICAL)



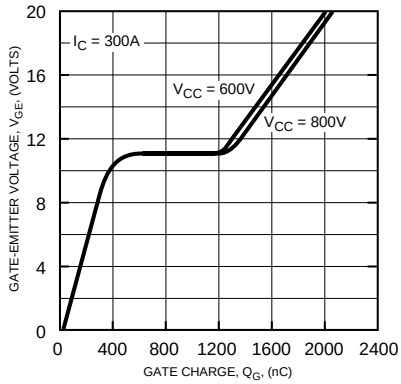
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



GATE CHARGE, V_{GE}



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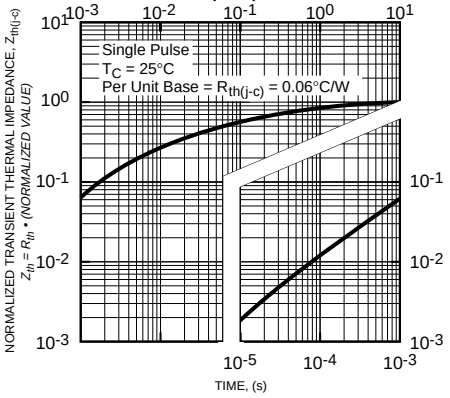
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (FWDi)